



Product Change Notification / RMES-11LZPK817

Date:

25-Mar-2021

Product Category:

Interface- LIN Transceiver

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4569 Final Notice: Qualification of MMT as an additional assembly site for ATA6663-FAQWxx device family available in 8L VDFN (3x3x1.0mm) package.

Affected CPNs:

[RMES-11LZPK817_Affected_CPN_03252021.pdf](#)

[RMES-11LZPK817_Affected_CPN_03252021.csv](#)

Notification Text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section to the right.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .csv).

Description of Change:

Qualification of MMT as an additional assembly site for ATA6663-FAQWxx device family available in 8L VDFN (3x3x1.0mm) package.

Pre Change:

Assembled at ASCL using palladium coated gold (AuPd1) bond wire, EN-4900G die attach, G700LA mold compound and

C7025 lead frame material without lead lock.

Post Change:

Assembled at ASCL using palladium coated gold (AuPd1) bond wire, EN-4900G die attach, G700LA mold compound and C7025 lead frame material without lead lock.

or

Assembled at MMT using palladium coated copper with gold flash (CuPdAu) bond wire, 3280 die attach, G700LTD mold compound and C194 lead frame material with lead lock.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	ASE Group Chung-Li (ASCL)	ASE Group Chung-Li (ASCL)	Microchip Technology Thailand (Branch) (MMT)
Wire material	AuPd1	AuPd1	CuPdAu
Die attach material	EN-4900G	EN-4900G	3280
Molding compound material	G700LA	G700LA	G700LTD
Lead frame material	C7025	C7025	A194
Lead Lock (Locking Hole)	No	No	Yes

Impacts to Data Sheet:

Yes, refer to POD comparison table.

POD Comparison:

Dimensions in mm

		ASCL			MMT		
Dimension	Symbol	Min	Nom	max	Min	Nom	Max
Overall height	A	0.80	0.85	0.90	0.80	0.90	1.00
Wettable flank step length	D3	-	-	0.040	-	-	0.085
Wettable flank step height	A4	0.10	-	0.15	0.10	-	0.19

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

March 16, 2021 (date code: 2112)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	February 2021				March 2021				
Workweek	06	07	08	09	10	11	12	13	14
Qual Report Availability			X						
Final PCN Issue Date			X						
Estimated Implementation Date							X		

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

February 15, 2021: Issued final notification. Attached the qualification report and added the estimated first ship date by March 16, 2021. **March 25, 2021:** Re-issued final notification. Corrected typo error of package type from VQFN to VDFN in PCN Letter and Qualification report.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_RMES-11LZPK817_Qual_Report.pdf](#)

[PCN_RMES-11LZPK817_Pre and Post Change_Summary.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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